

WHAT IS CLAIMED IS:

1. A method for cleaning a capillary tube for use in a wire bonding tool, the method comprising the step of:

applying an ultrasonic wave to the capillary tube, with a tip portion of the capillary tube being immersed in a cleaning solution, and with a cleaning wire being inserted at least in the tip portion of the capillary tube.

2. The method as defined in claim 1, further comprising, prior to said applying step, the step of grinding the tip portion of the capillary tube by using an abrasive sheet, with at least the tip portion of the capillary tube being empty.

3. The method as defined in claim 2, wherein said grinding step comprises the step of moving the capillary tube.

4. The method as defined in claim 2, wherein said grinding step comprises the step of rotating the abrasive sheet.

5. The method as defined in claim 1, wherein the cleaning wire is made of tungsten.

6. A cleaner for cleaning a capillary tube for use in a wire bonding tool, the cleaner comprising:

a cleaning wire to be inserted in the capillary tube;
a cleaning tank for receiving therein a cleaning solution;

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an ultrasonic wave generator for applying an ultrasonic wave to the capillary tube, with a tip portion of the capillary tube being immersed in the cleaning solution, and with the cleaning wire being inserted at least in the tip portion of the capillary tube.

7. The cleaner as defined in claim 6, further comprising an abrasive sheet for grinding the tip portion of the capillary tube.

8. The cleaner as defined in claim 6, wherein the cleaning wire is made of tungsten.